1200W

4000W+1200W

Heating Feature

Both top and bottom heating power up to 1200W, brushless motor, the max airflow up to 60L/S, large infrared preheating area（4000W）at the bottom side, even heat distribution.

Features

High automation, one-touch for rework, soldering, pick-up and placement of chip, easy operation.

Large power brushless DC fan, closed loop sensor, microcomputer zero trigger control, large volume air with constant temperature.
No need of external air source, flexible application.

Seven-phase temperature zone, can be used for light-reflecting BGA, multi-layer BGA and metallic shielding case, POP.

Integrated design, the heating and alignment systems integrate well.

Dichromatic optical prism alignment, joystick control.

Transverse flow fan, air speed controllable, cool down bottom heating area and PCB as per process requirement.

QUICKSOFT interface, operation access and profile analysis functions available, can analyze preheating speed, peak temperature, temperature holding time and cooling rate effectively.

Various nozzles, easy replacement.

Applications: PC, Server Motherboard, IPC, Terminal and large PCB rework BGA or CONNECT.

Specifications

General Power	6600W(max)
Voltage	220V AC 50HZ
Hot Air Heating Temperature	400°C(Max)
Bottom Preheating Temperature	400°C(Max)
Power of Top Heater(hot Air)	1200W
Power of Bottom Heater(hot Air)	1200W
Power of Bottom Heater(infrared Preheating)	4000W
Hot Air Flow	60L/S
Max PCB Size	600 x 650mm
BGA Size Range	2*2mm 60*60mm
Placement Precision	±0.02mm
Air Speed Of Side Cooling Fan	≤3.5m³/min
Camera	36*12 times magnifying
	Horizontal resolution 500 lines
	PAL format
External K-type Sensor	5 ports
Communication	USB
Weight	160kg
Dimensions	1200(L)mm x 800(W)mm x 940(H)mm